

# SOT1706-1

LPGA672, plastic, low profile ball grid array; 672 balls; 1 mm pitch; 35 mm x 35 mm x 0.95 mm body

23 August 2018

Package information

## 1 Package summary

<b>Terminal position code</b>	B (bottom)
<b>Package type descriptive code</b>	LPGA672
<b>Package style descriptive code</b>	LPGA (low profile ball grid array)
<b>Package body material type</b>	P (plastic)
<b>Mounting method type</b>	S (surface mount)
<b>Issue date</b>	24-02-2016
<b>Manufacturer package code</b>	98ARE10569D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	-	35	-	mm
package width	-	35	-	mm
package height	-	0.95	-	mm
nominal pitch	-	1	-	mm
actual quantity of termination	-	672	-	



2 Package outline

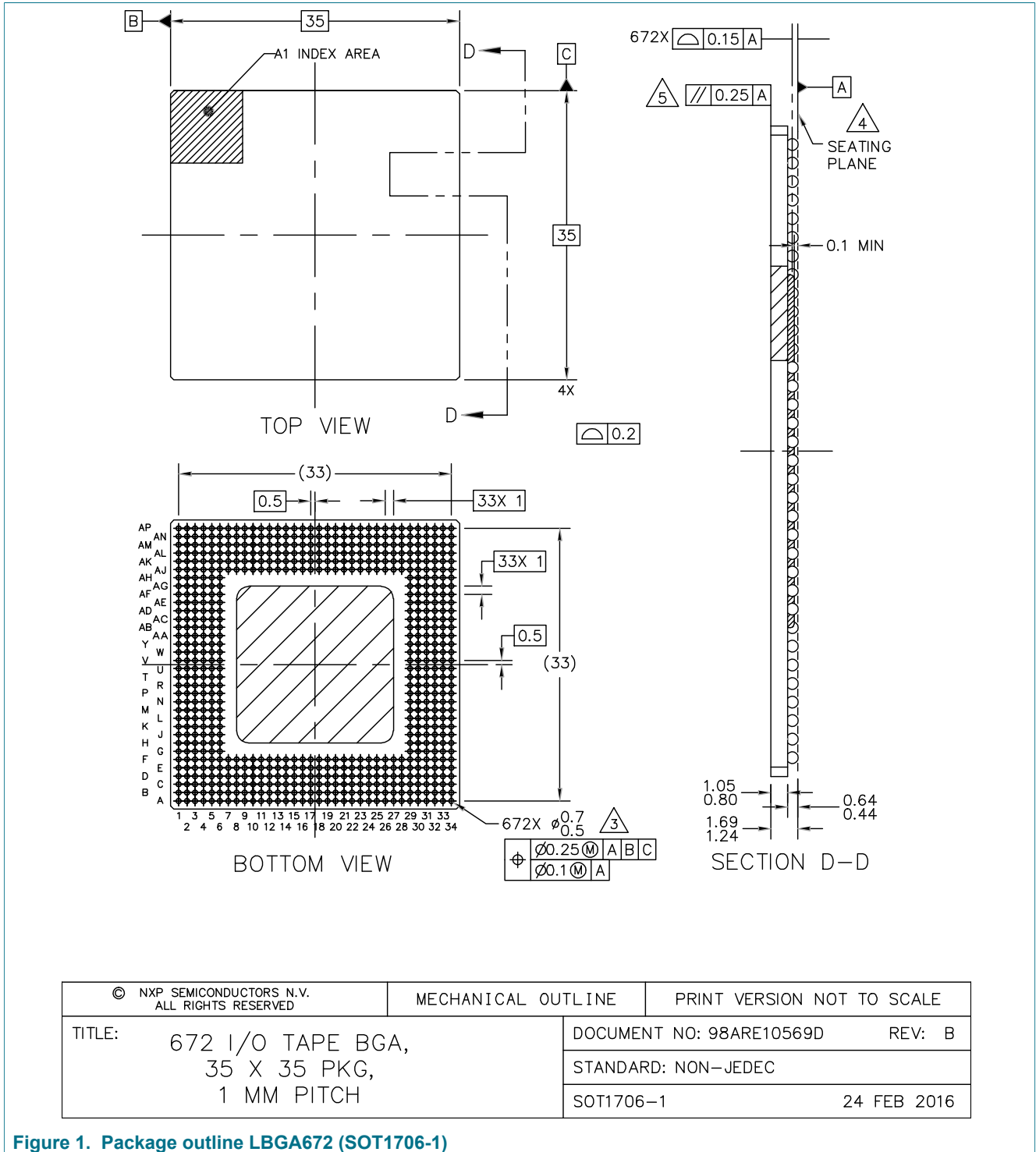


Figure 1. Package outline LPGA672 (SOT1706-1)

NOTES:

1. ALL DIMENSIONS IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM A.
4. DATUM A, THE SEATING PLANE, IS DETERMINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
5. PARALLELISM MEASUREMENT SHALL EXCLUDE ANY EFFECT OF MARK ON TOP SURFACE OF PACKAGE.

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TITLE: 672 I/O TAPE BGA, 35 X 35 PKG, 1 MM PITCH	DOCUMENT NO: 98ARE10569D		REV: B
	STANDARD: NON-JEDEC		
	SOT1706-1	24 FEB 2016	

Figure 2. Package outline note LPGA672 (SOT1706-1)

### 3 Legal information

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